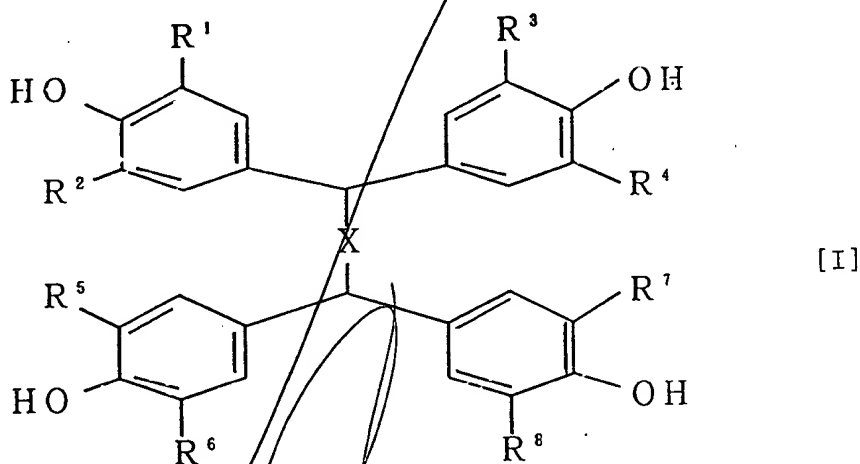


AMENDMENT A
(37 C.F.R. §1.111)

IN THE CLAIMS:

Please substitute Claims 1-3 and 5 with replacement Claims 1-3 and 5 in accordance with 37 C.F.R. §1.121. A version of the claims depicting the changes is shown as an attachment to this Amendment. Please cancel Claim 4 without disclaimer to its content and without prejudice to its subsequent reintroduction into this or a future patent application.

1. (Amended) A clathrate curative for epoxy resins comprising:
a tetrakisphenol compound represented by a general formula [I]



wherein X represents $(CH_2)_n$, n is 0, 1, 2, or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

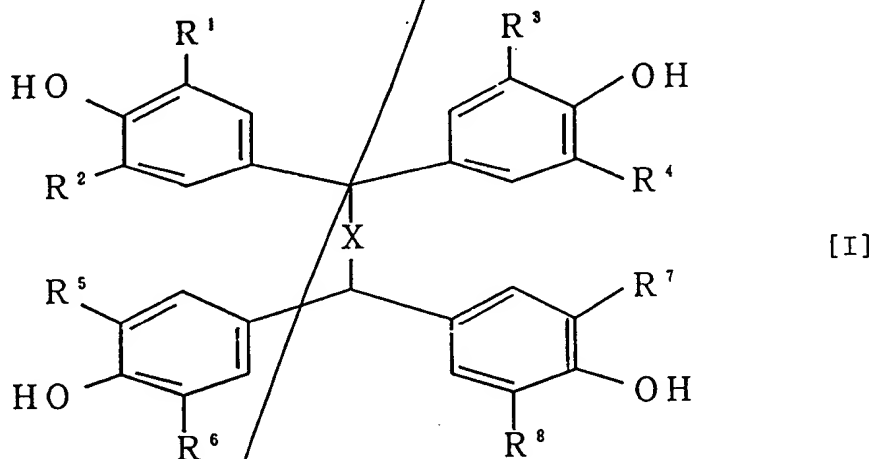
a compound other than the tetrakisphenol compound, which reacts with epoxy groups of an epoxy resin to cure the resin,

wherein the clathrate is present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.

2. (Amended) A clathrate curing accelerator for epoxy resins comprising:

a tetrakisphenol compound represented by a general formula

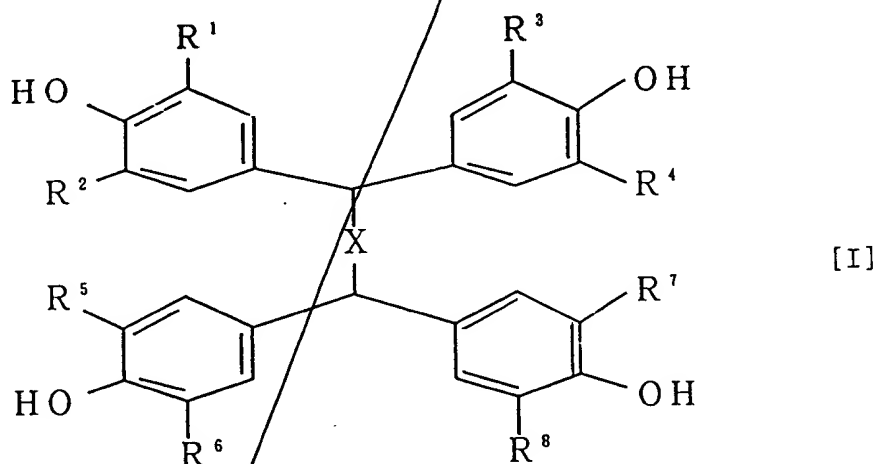
[I];



wherein X represents $(CH_2)_n$, n is 0, 1, 2, or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound accelerating the curing of a compound other than the tetrakisphenol compound, which reacts with epoxy groups of an epoxy resin to cure the resin, wherein the clathrate is present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.

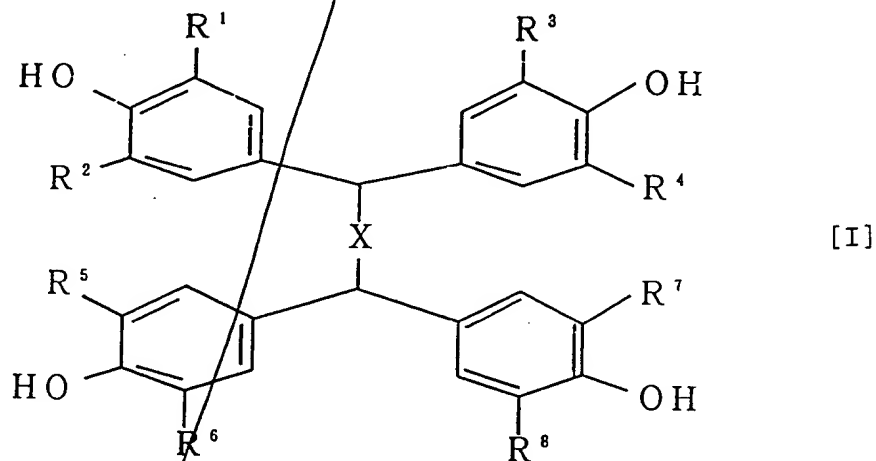
3. (Amended) Epoxy resin compositions comprising:
 an epoxy resin, said epoxy resin containing a clathrate
 curative, said clathrate curative being a tetrakisphenol compound
 represented by a general formula [I]



wherein X represents $(CH_2)_n$, n is 0, 1, 2, or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound other than the tetrakisphenol compound, which reacts with epoxy groups of the epoxy resin to cure the resin, wherein the clathrate curative is present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups; and/or

a clathrate curing accelerator, said clathrate curing accelerator being a tetrakisphenol compound represented by a general formula [I];



wherein X represents $(CH_2)_n$, n is 0, 1, 2, or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound accelerating the curing of a compound other than the tetrakisphenol compound, which reacts with epoxy groups of the epoxy resin to cure the resin, wherein the clathrate curing accelerator is present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.

5. (Amended) Epoxy resin compositions comprising:

an epoxy resin;

a clathrate according to Claim 1; and

a clathrate curing accelerator according to Claim 2;

wherein the clathrates are present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.